

FUTURE TECHNOLOGIES SYMPOSIUM

OCP Global Summit

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RUNTIME MANAGEMENT OF THE COMPOSABLE MEMORY

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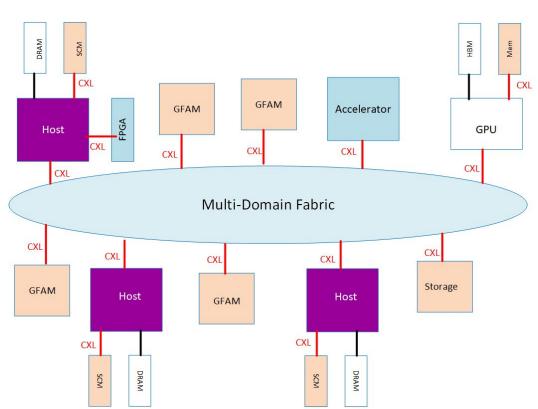
AGENDA

- Paradigm Shift and Memory Composability Progression
- Runtime Memory Management
- Tiered Memory
 - NUMA domains and Page Migration
- Multi-Type Memory Management
 - Persistent and Combined Memory/Storage operation
- Runtime Memory Pooling and Borrowing



PARADIGM SHIFT

- Scalable, high-speed CXL[™] Interconnect and PIM (Processing in Memory) contribute to the paradigm shift in memory intensive computations
- Efficiency Boost of the next generation data center
 - Management of the Host/Accelerator subsystems combined with the terabytes of the Fabric Attached Memory
 - Reduced complexity of the SW stack combined with direct access to multiple memory technologies





MEMORY COMPOSABILITY PROGRESSION

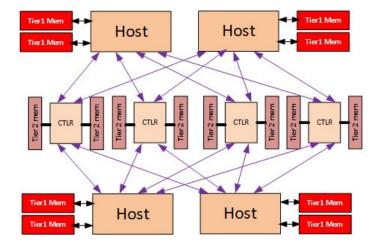
Mem Direct Attach

Memory Scale-Out

Host Received of the second se

- Workloads/ applications benefiting from memory capacity
- Design optimization for {BW/\$, Memory Capacity/\$, BW/core}

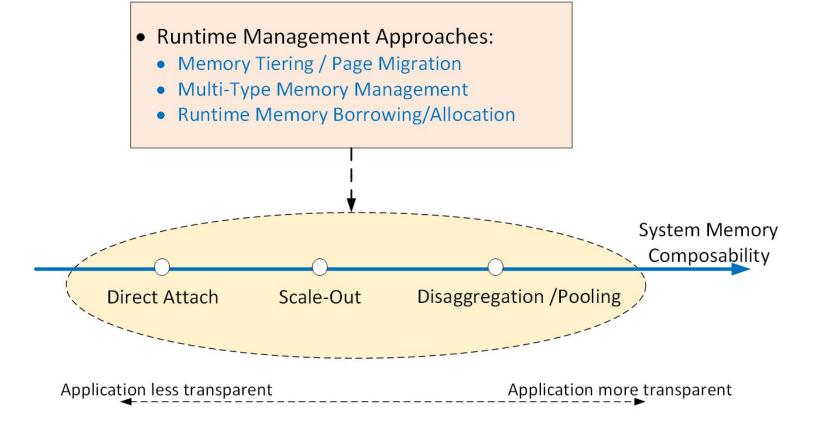
Mem Pooling & Disaggregation



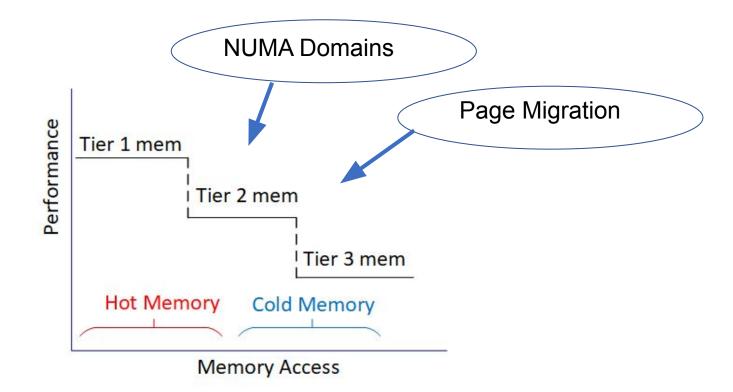
- Addresses the cost and underutilization of the memory
- Multi-domain Pooled Memory memory in the pool is allocated/ released when required



RUNTIME MEMORY MANAGEMENT



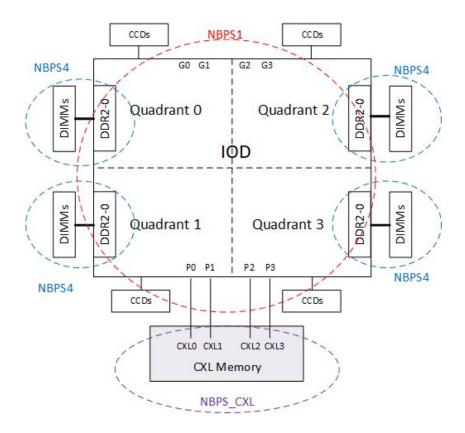
TIERED MEMORY





TIERED MEMORY

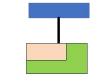
- Exposed to the HV, Guest OS, Apps
- OS-assisted optimization of the memory subsystem
- Base on ACPI objects -SRAT/SLIT/HMAT

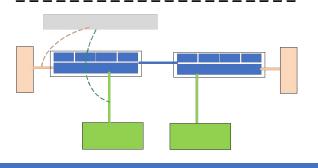




TIERED MEMORY

PAGE MIGRATION

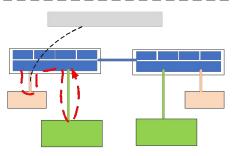




SW Assisted Page Migration

- Active page migration between Far and Near memories
- HV/Guest migrates hot pages into Near Mem and retire cold pages into Far Mem
- Focused DMA to transfer required datasets from the Far to Near Mem





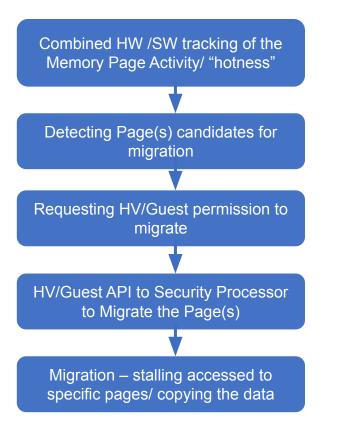
DRAM as a cache optimization

- HW managed Hot Dataset
- Near Mem Miss redirected to the Far Mem
- App/ HV unawareness



TIERED MEMORY SW ASSISTED PAGE MIGRATION

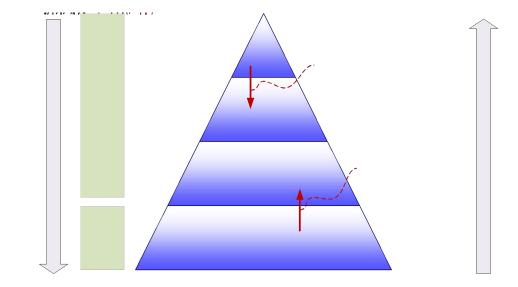
- Page "hotness" –combined action of the HW and SW tracking
- HV/Guest authorization of the migration
- Security Processor as a root of trust for performing the migration





PERSISTENT MEMORY

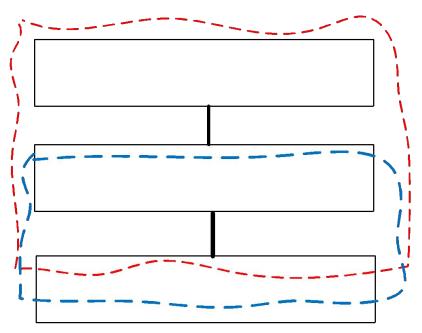
- PMEM aware apps (reduced data movement for power fail recovery, DB load time, etc.)
- Instant-on computer systems with persistent state
- Fully memory-mapped systems (no storage IO protocols)





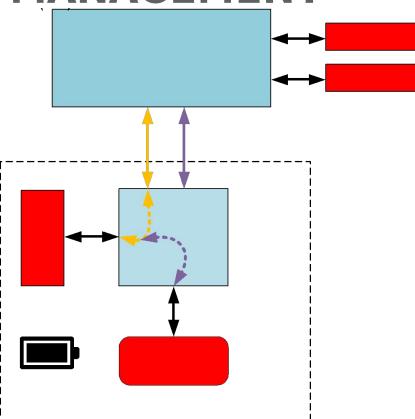
PERSISTENT MEMORY

- Global Persistent Data Flush (GPF)
- In the event of imminent power failure/hazardous events
- Associated with Enhanced Endurance Region
- No application awareness
- Basic Persistent Flush (BPF)
- Limited to Basic Endurance Region
- Applicable to the systems with limited hold-up
- Requires SW involvement in periodic data flush to endurance



COMBINED MEMORY/STORAGE OPERATION

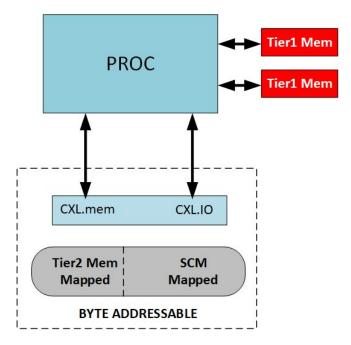
- Tier2 to NVM Data Transfer on power failure under battery power
- No data loss in the event of power failure while achieving full memory throughout (with Tier1/ Tier2) during normal operation
- Battery hold-up control to minimize the system power
- Dirty page tracking to speed up the Tier 2-> NVM data transfer





COMBINED MEMORY / STORAGE OPERATION

- High-performance storage on memory bus with flexible access (64B to 512B)
- Design scalability for {density, power, latency, pricing} through SW based memory tiering selection
- Diskless Server with Storage disaggregation
- Leverages existing software paradigm with application transparent integration (does not require persistent memory ecosystem)
- On-demand page re-mapping between Storage and Memory with zero DMA

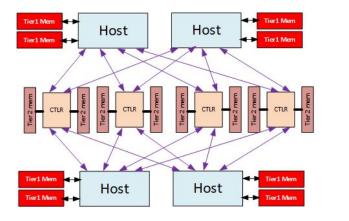


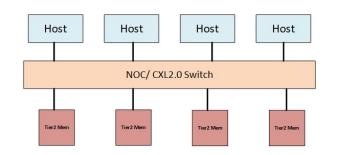


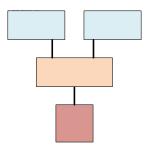
RUNTIME MEMORY ALLOCATION / POOLING

FABRIC ATTACHED MEMORY

- Multiple structures serve for fabric level memory pooling/ borrowing
- Combination of the private (dedicated to specific host) and shareable memory ranges
- Protection of the memory regions from unauthorized guests and hypervisor
- Borrowing/ Lending of the memory ranges between Hosts is regulated by the fabric aware SW layer (i.e., Fabric Manager)





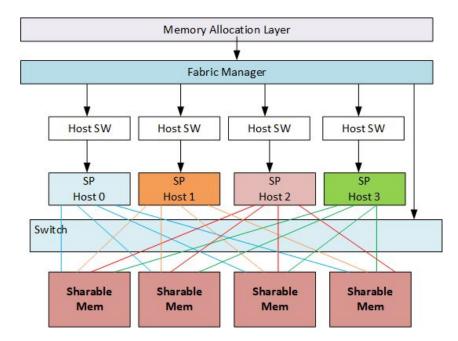




RUNTIME MEMORY ALLOCATION / POOLING

FABRIC ATTACHED MEMORY

- Memory Allocation Layer communicates <new memory allocation per Host> based on the system/apps needs
- Fabric Manager adjusts the fabric settings and communicates new memory allocations to the Host SW
- Host SW Invokes Hot Add/Hot Removal method to increase/ reduce (or offline) an amount of memory allocated to the Host
 - In some instances, Host SW can directly invoke SP to adjust the memory size allocated to the Host
- On-die Security Processor (Root of Trust) is involved in securing an exclusive access to the memory range





SUMMARY

- Composable Disaggregated Memory is the key approach to address the cost and underutilization of the System Memory
- Further investment in the Runtime Management of the Composable & Multi-Type memory structures is required to maximize the system level performance across multiple use-cases
- Application Transparency is another goal of efficient Runtime Management by abstracting away an underlying fabric/memory infrastructure

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